Ultra High Performance BGA Cooling Solutions w/ maxiGRIP™ Attachment*

DIGI-KEY PART # ATS1002-ND

ATS PART # ATS-50210B-C2-R0

Features & Benefits

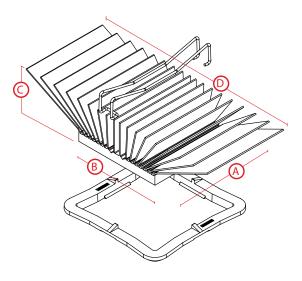
maxiFLOW[™] design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling

maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB

Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards

Comes preassembled with high performance, phase changing, thermal interface material

Designed for standard height components from 3 to 4.5mm





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Innovations in Thermal Management®

SOLUTIONS, INC.

Thermal Performance Table

AIR VELOCITY			THERMAL RESISTANCE		
FT/MIN		M/S	°C/W (UNDUCTED)	°C/W (DUCTED)	
	200	1.0	11.9	8.8	
300		1.5	9.5		
400		2.0	8.2		
500		2.5	7.3		
600		3.0	6.7		
700		3.5	6.2		
800		4.0	5.8		

Product Details[†]

DIMENSION A	DIMENSION B	DIMENSION C [§]	DIMENSION D	TIM [‡]	FINISH
21	21	7.5	34.56	C1100F	BLUE-ANODIZED

For further technical information, please contact Advanced Thermal Solutions, Inc. at **1-781-769-2800** or **www.qats.com**

* RoHS Compliant

‡ TIM = Thermal Interface Material

† Dimensions are measured in millimeters

Dimensions A & B refer to component size
Dimension C = the height of the heat sink of

§ Dimension C = the height of the heat sink shown above and does not include the height of the attachment method



To place an order, please visit www.digikey.com